CLAIMS

1. A resin sheet for sealing an electronic device, wherein the resin sheet is obtained by subjecting a kneaded product obtained through kneading an epoxy resin, a phenol resin, a thermoplastic resin, a filler, and a curing accelerator to plastic processing to form the kneaded product into a sheet shape, wherein an average particle size of the thermoplastic resin is 5 to 500 μm; and wherein the curing accelerator is an imidazole curing accelerator, the resin sheet having an exothermic onset temperature of 120°C or higher measured with a differential scanning calorimeter and an exothermic peak temperature of 150 to 200°C.

2. The resin sheet for sealing an electronic device according to claim 1, wherein an area in a range of the exothermic peak temperature ± 30°C in a DSC curve measured with the differential scanning calorimeter is 70% or more to an entire exothermic peak area.

3. The resin sheet for sealing an electronic device according to claim 1 or 2, wherein a minimum melt viscosity after the resin sheet is stored under a condition of 25°C for 4 weeks is not more than 2 times a minimum melt viscosity before the storage.

4. The resin sheet for sealing an electronic device according to any of claims 1 to 3, wherein a content of

filler in the resin sheet for sealing an electronic device is 70 to 90% by volume.

5. The resin sheet for sealing an electronic device according to any of claims 1 to 4, which is obtained by subjecting a kneaded product obtained through kneading an epoxy resin, a phenol resin, a thermoplastic resin, a filler, and a curing accelerator to plastic processing to form the kneaded product into a sheet shape.

6. The resin sheet for sealing an electronic device according to any of claims 1 to 5, wherein the imidazole curing accelerator is a latent curing accelerator.

7. A method of manufacturing an electronic device package, the method comprising:

a laminating step of laminating the resin sheet for sealing an electronic device according to any of claims 1 to 6 on one or a plurality of electronic devices so as to cover the electronic devices; and

a sealing body forming step of curing the resin sheet for sealing an electronic device to form a sealing body.